

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	351	425/128.col.s.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2009/06/08 15:13
L2	18033	257/787.col.s. 257/ e21.502.col.s. 257/ e21.504.col.s. 257/ e21.705.col.s. 257/ e23.116.col.s. 257/ e23.125.col.s. 438/108. col.s. 438/124.col.s. 438/126.col.s. 438/127.col.s. 156/500.col.s. 425/117.col.s. 425/125.col.s. 425/128.col.s.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2009/06/08 15:14
L3	388	L2 and ((encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity feed\$6 assembl\$6) same (edge project\$6) same (movable displac\$6 support receiv\$6 force part))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2009/06/08 15:14
L4	424	(encapsulat\$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity space open\$6) same (feed\$6 assembl\$6) same (edge project\$6)	US-PGPUB; USPAT	OR	ON	2009/06/08 15:31

		same (mov\$6 displac \$6 adjust\$6) same (support receiv\$6 force part)				
L5	228	((encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open\$6) and (feed\$6 assembl\$6) and (edge project\$6) and (mov\$6 displac\$6 adjust\$6) and (support receiv\$6 force part))	FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/08 15:44
L6	547	((encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open\$6) and (feed\$6 assembl\$6) and (edge project\$6) and (mov\$6 displac\$6 adjust\$6) and (support receiv\$6 force part)).clm.	US-PGPUB	OR	ON	2009/06/08 15:49
L9	7	((encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) near4 (semiconductor silicon die dice chip wafer fragment integrated ic component)) and ((carrier substrate board pwb pcb base) near6 (cavity space open\$6)) and ((feed \$6 assembl\$6) near6	US-PGPUB	OR	ON	2009/06/08 15:58

((edge project\$6)) and
((mov\$6 displac\$6
adjust\$6) near6
(support receiv\$6
force part))).clm.

6/8/09 4:00:18 PM

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